

ALPHA[®] CVP-520

LOW MELTING POINT NO-CLEAN LEAD-FREE HALOGEN FREE SOLDER PASTE

DESCRIPTION

ALPHA[®] CVP-520 is designed to enable low temperature surface mount assembly technology. The lead-free alloy in **ALPHA[®] CVP-520** has a melting point below 140°C, and has been successfully used with peak reflow profiles between 155°C and 190°C. The flux residue from **ALPHA[®] CVP-520** is clear, colorless, and provides excellent electrical resistivity, exceeding industry standards.

This product enables the elimination of an extra wave or selective wave soldering process when temperature sensitive through hole components are used in an assembly. Eliminating a wave soldering or selective soldering step can significantly lower the cost of producing an electronic assembly, increase daily throughput, eliminate the need for managing bar solder and wave soldering flux supplies and eliminate the need for pallets. The carefully selected Sn/Bi/Ag alloy in **ALPHA[®] CVP-520** was selected to give the lowest melting point, lowest pasty range during melting and re-solidification, along with a very fine grain structure, offering maximum resistance to thermal cycle based fatigue. The alloy also yields very low voiding BGA solder joints, even when a traditional SAC alloy sphere is used.

The use of **ALPHA[®] Exactalloy[™]** performs may enable the elimination of selective wave soldering by providing additional solder volume when needed, especially when rectangular leads are inserted into round through holes.

All components used with **ALPHA[®] CVP-520** must be lead-free to eliminate the formation of tin/lead/bismuth intermetallic which has a melting point under 100°C.

Value in Use

- Enables elimination of a second or third reflow cycle when temperature sensitive components or connectors are used.
- Reduces energy consumption in reflow ovens versus standard lead free alloys.
- Reduces reflow process cycle time.
- Delivers 8+ Hour stencil life.
- Potential elimination of bar solder, wave soldering flux and energy costs associated with wave soldering.
- Compatible with all commonly used lead free surface finishes (Entek HT; Alpha Star Immersion Silver, Immersion Tin, Ni/Au, SACX HASL, etc.)
- Excellent resistance to random solder balling- minimizing rework and increasing first time yield.
- Low temperature reflow profiles may enable the use of less expensive printed circuit board substrates.
- Meets highest IPC 7095 voiding performance (Class III).
- Delivers very high in-circuit pin test yields, minimizing costly false negative test results.
- Provides excellent electrical reliability properties, halogen and halide-free material.
- Compatible with either nitrogen or air reflow.

PRODUCT INFORMATION

<u>Alloys:</u>	42%Sn/57.6%Bi/0.4%Ag 42%Sn/57%Bi/1.0%Ag, available upon request
<u>Powder Size:</u>	Type 3, (25-45µm per IPC J-STD-005);
<u>Residues:</u>	Approximately 5% by (w/w)
<u>Packaging Sizes:</u>	500gram jars, 6" & 12" cartridges
<u>Flux Gel:</u>	CVP-520 Flux Gel is available in 10cc and 30cc syringes for rework applications.
<u>Lead Free:</u>	Complies with RoHS Directive 2002/95/EC.

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APPLICATION

Formulated for both standard and fine pitch stencil printing, at print speeds of between 25mm/sec (1.0"/sec) and 100mm/sec (4"/sec), with stencil thickness of 0.100mm (0.004") to 0.150mm (0.006"), particularly when used in conjunction with ALPHA® Stencils. Blade pressures should be 0.18-0.27 kg/cm of blade (1.0 -1.5 lbs/inch), depending upon the print speed. The higher the print speed employed, the higher the blade pressure that is required to prevent smearing on the stencil. Examples of successful reflow profiles are outlined below. Generally, peak temperatures of 155°C to 190°C have proven effective.

SAFETY

While the **CVP-520** flux system is not considered toxic, its use in typical reflow will generate a small amount of reaction and decomposition vapors. These vapors should be adequately exhausted from the work area. Consult the MSDS for additional safety information.

STORAGE

CVP-520 should be stored in a refrigerator upon receipt at 0° to 10°C (32 to 50°F). **CVP-520** should be permitted to reach room temperature before unsealing its package prior to use (see handling procedures on page 3). This will prevent moisture condensation build up in the solder paste.

CVP-520 TECHNICAL DATA		
CATEGORY	RESULTS	PROCEDURES/REMARKS
CHEMICAL PROPERTIES		
Activity Level	ROL-0 = J-STD Classification	IPC J-STD-004
Halide Content	Halide free (by titration). Passes Ag Chromate Test	IPC J-STD-004
Copper Mirror Test	Pass	IPC J-STD-004
Copper Corrosion Test	Pass, (No Evidence of Corrosion)	IPC J-STD-004
ELECTRICAL PROPERTIES		
SIR (IPC 7 days @ 85°C/85%RH)	Pass	IPC J-STD-004 {Pass = 1 x 10 ⁸ ohm min}
SIR (Bellcore 96 hours @ 35 C/85%RH)	Pass	Bellcore GR78-CORE {Pass = 1x10 ¹¹ ohm min}
Electromigration (JIS Z 3197 @ 85°C/85%RH 40V DC 1000 hours)	Final Reading > 10 ¹⁰ ohms No Migration After 1000 hrs = Pass	JIS Z 3197 1999
PHYSICAL PROPERTIES		
	M 21 Viscosity (Malcolm viscometer @10 RPM, 25°C)	90% Metal, Type # 3 Powder
Color	Clear, Colorless Flux Residue	
Tack Force vs. Humidity (t = 8 hours)	Pass - Change of <1g/mm ² over 24 hours at 25% and 75 % Relative Humidity	IPC J-STD-005
	Pass - Change of <10% when stored at 25±2°C and 50±10% relative humidity.	JIS Z3284 Annex 9
Viscosity	90% metal load designated M 21 for printing.	Malcom Spiral Viscometer; J-STD-005
Solderball	Acceptable	IPC J-STD-005
Stencil Life	>8 hours	@50%RH, 23°C (74 F)
Spread	>87%	JIS-Z-3197: 1999 8.3.1.1



CVP-520 Processing Guidelines			
STORAGE & HANDLING	PRINTING	REFLOW (See Figure #1)	CLEANING
<p>*Refrigerate to guarantee stability at (0-10)°C, (32-50)°F</p> <p>*Shelf life of refrigerated paste is >3 months, Actual TBD</p> <p>*Paste can be stored for 2 weeks at room temperatures up to (25°C/77°F) prior to use</p> <p>*When refrigerated, allow sealed paste container to warm to room temperature for up to four hours. Paste must be ≥ (19°C/66°F) before processing. Verify paste temperature with a thermometer to ensure paste is (19°C/66°F) or greater before set-up. Printing can be performed at temperatures up to (29°C/84°F).</p> <p>*Do not remove worked paste from stencil and mix with unused paste in jar. This will alter rheology of unused paste.</p> <p>*These are starting recommendations and all process settings should be reviewed independently.</p> <p>Working conditions: (19 to 29)°C on the stencil.</p>	<p>STENCIL: Recommended Cookson Electronics ALPHA CUT or ALPHA FORM stencils @ (0.100 - 0.150 mm), (4-6 mil) thick for (0.4-0.5mm) (0.016" or 0.020") pitch. Stencil design is subject to many process variables. Contact your local Cookson Electronics stencil site for advice.</p> <p>SQUEEGEE: Metal (recommended)</p> <p>PRESSURE: (0.18-0.27) kg/cm of squeegee length (1.0-1.5 lbs./inch).</p> <p>SPEED: (25 to 100mm) per second (1.0 to 4.0 inches) per second.</p> <p>PASTE ROLL: (1.5-2.0 cm) diameter and make additions when roll reaches 1-cm, (0.4") diameter (min). Max roll size will depend upon blade height.</p> <p>STENCIL RELEASE SPEED: 3 - 10 mm (0.12 to 0.4 inches)/ sec. Lift Height: 8 - 14mm (.31 -.55")</p>	<p>ATMOSPHERE: Clean-dry air or nitrogen atmosphere.</p> <p>PROFILE: See Figure #1 Acceptable reflow/coalescence and IPC Class III voiding were obtained with the given profiles</p> <p>Note: Refer to component and board supplier data for thermal properties at elevated temperatures. Lower peak temperatures require longer TAL for improved joint cosmetics.</p>	<p>ALPHA CVP-520 residue is designed to remain on the board after reflow. If reflowed residue cleaning is required, ALPHA BC-2200 aqueous cleaner is recommended. For solvent cleaning, agitation for 5 min in the following cleaners is recommended:</p> <ul style="list-style-type: none"> - ALPHA SM-110E - Bioact™ SC-10E - Kyzen Micronox MX2501 <p>Misprints and stencil cleaning may be done with ALPHA SM-110E, ALPHA SM-440, ALPHA BC-2200 and Bioact™ SC-10E cleaners.</p>

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Parameter	Guideline
Atmosphere	Air or N2
SnBiAg (42/57.6/0.4) alloy	138°C (near eutectic)
Setting Zone	Optimal Dwell Period
40°C to 138°C	2:10 to 4:00 min.
125°C to 138°C	0:30 to 1:30 min
100°C to 138°C	1:15 to 2:00 min.
TAL (138°C)	30 - 90 sec.
Peak temperature	<155 °C - 190°C
Joint cool down rate from 170°C	>3°C - 8°C

Figure #1 – CVP-520 Reflow Profile Envelope

